

Final Product Change Notification

Issue Date: 02-Sep-2015 Effective Date: 14-Dec-2015

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201504012F01



Management Summary

Enable ASEN as a second source assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types

Change Category

[] Wafer Fab process	[] Assembly Process	[X] Product Marking	[] Design
[] Wafer Fab materials	[] Assembly Materials	[] Electrical spec./Test coverage	[] Mechanical Specification
[] Wafer Fab location	[X] Assembly Location	[X] Test Location	[] Packing/Shipping/Labeling

PL-HSI & MCU HVQFN32/HVQFN48 ASEN second source assembly & test

Details of this Change

- Enable ASEN as an assembly and test location for numerous PL-HSI and MCU (HVQFN32 & HVQFN48 based) product types.
- Assembly Material types and Test platforms will be the same
- NXP APK (the parent factory) provided loadboards for ATE use,
- The two MCU parts (LPC822M101JHI33 & LPC824M201JHI33) will have a minor change in line c marking. The assembly site 'X' will show in the marking of Line c for ASEN material.

Why do we Implement this Change

- The purpose is to expand our production capacity and to increase planning flexibility.
- Minor marking change to the ASEN assembled MCU parts (LPC822M101JHI33 & LPC824M201JHI330) will allow to allow better balance of traceability.

APK assembled material will remain as currently marked.

Identification of Affected Products

Top side marking and/or labels will have different marking code for new assembly center.

The marking of the assembly center is setup in the 3rd row where "X" indicates the assembly center ASEN.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 17-Jul-2015

Impact

no impact to the product's functionality anticipated.

No material changes or test platform changes will occur.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification Issue Date Effective Date Title

201504012A 27-Apr-2015 PL-HSI & MCU HVQFN32/HVQFN48 ASEN second source assembly & test

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 02-Oct-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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